CALL FOR PAPERS

ISQED 2011

12th International Symposium on

QUALITY ELECTRONIC DESIGN



March 14-16, 2011 - Hyatt Regency, Santa Clara, CA, USA

www.isqed.org















The International Symposium on Quality Electronic Design (ISQED) is the leading Electronic Design & Design Automation conference, aimed at bridging the gap among electronic design tools and processes, integrated circuit technologies, processes & manufacturing, to achieve design quality. ISQED is the pioneer and leading international conference dealing with design for manufacturability and quality issues front-to-back. ISQED emphasizes a holistic approach toward electronic design and intends to highlight and accelerate cooperation among the IC Design, EDA, Semiconductor Process Technology and Manufacturing communities. ISQED spans three days, Monday through Wednesday, in three parallel tracks, hosting over100 technical presentations, several keynote speakers, panel discussions, workshops/tutorials and other informal meetings. Conference proceedings are published by IEEE and posted in the digital library. Proceedings CD ROMs are published by ACM. In addition, continuing the tradition of reaching a wider readership in the IC design community, ISQED will continue to publish special issues in leading journals. The authors of high quality papers will be invited to submit an extended version of their papers for the special IEEE journal issues, such as TCAD, etc.

Papers are requested in the following areas

A pioneer and leading multidisciplinary conference, ISQED accepts and promotes papers related to the manufacturing, design and EDA. Authors are invited to submit papers in the various disciplines of high level design, circuit design (digital, analog, mixed-signal, RF), test & verification, design automation tools; processes; flows, device modeling, semiconductor technology, and advance packaging. The details of various topics of paper submission are as follows:

Design for Manufacturability/Yield & Quality (DFM/DFY/DFQ)

Physical Design, Methodologies & Tools (PDM)

Design Verification and Design for Testability (DVFT)

EDA Methodologies, Tools, Flows & IP Cores; Interoperability and Reuse(EDA)

Robust & Power-conscious Devices, Interconnects, and Circuits (PCC)

Emerging/Innovative Process & Device Technologies and Design Issues (EDT)

Package - Design Interactions & Co-Design (PDI)

Design of Reliable Circuits and Systems (DFR)

System-level Design, Methodologies & Tools (SDM)

Submission of Papers

Paper submission must be done on-line through the conference web site at **www.isqed.org**. The guidelines for the final paper format are provided on the conference web site. Authors should submit FULL-LENGTH, original, unpublished papers (Minimum 4, maximum 6 pages) along with an abstract of about 200 words. To permit a blind review, do not include name(s) or affiliation(s) of the author(s) on the manuscript and abstract. The complete contact author information needs to be entered separately. Please check the as-printed appearance of your paper before sending your paper. In case of any problems email isged2011@isged.org. Please note the following important dates:

Paper Submission Deadline Acceptance Notifications Final Camera-Ready paper September 30, 2010 November 23, 2010 January 3, 2011

www.isqed.org